# Field Stop Trench IGBT 650 V, 75 A

## AFGHL75T65SQDT

Using the novel field stop 4th generation IGBT technology and the Stealth Diode technology, AFGHL75T65SQDT offers the optimum performance with both low conduction and switching losses for a high efficiency operation in various applications, especially totem pole bridgeless PFC and DCDC block as well.

#### **Features**

- AEC-Q101 Qualified
- Maximum Junction Temperature:  $T_I = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.6 \text{ V (Typ.)} @ I_C = 75 \text{ A}$
- 100% of the Parts are Tested for I<sub>LM</sub> (Note 2)
- Fast Switching
- Tight Parameter Distribution
- RoHS Compliant

#### **Typical Applications**

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters
- Totem Pole Bridgeless PFC

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-to-Emitter Voltage	$V_{CES}$	650	V
Gate-to-Emitter Voltage Transient Gate-to-Emitter Voltage	V <sub>GES</sub>	±20 ±30	V
Collector Current (Note 1) @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	I <sub>C</sub>	80 75	Α
Pulsed Collector Current (Note 2)	$I_{LM}$	300	Α
Pulsed Collector Current (Note 3)	I <sub>CM</sub>	300	Α
Diode Forward Current @ $T_C = 25^{\circ}C$ @ $T_{C=100^{\circ}C}$	I <sub>F</sub>	80 75	Α
Pulsed Diode Maximum Forward Current	I <sub>FM(2)</sub>	300	Α
	P <sub>D</sub>	375 188	W
Operating Junction / Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

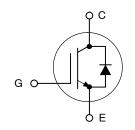
- 1. Value limit by bond wire
- 2.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  = 300 A,  $R_{G}$  = 17  $\Omega$ , Inductive Load
- 3. Repetitive Rating: pulse width limited by max. Junction temperature



### ON Semiconductor®

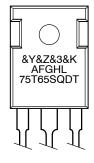
www.onsemi.com

75 A, 650 V **V<sub>CESat</sub>** = 1.6 **V** 





#### MARKING DIAGRAM



&Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = 3-Digit Data Code = 2-Digit Lot Traceability Code

AFGHL75T65SQDT = Specific Device Code

#### ORDERING INFORMATION

Device	Package	Shipping
AFGHL75T65SQDT	TO-247-3L	30 Units / Rail

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.4	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	0.65	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>.I</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•		•	•	
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	BV <sub>CES</sub>	650	-	-	V
Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V},$ $I_C = 1 \text{ mA}$	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	-	0.6	-	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	_	-	250	μА
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	_	±400	nA
ON CHARACTERISTICS						-
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 75 \text{ mA}$	V <sub>GE(th)</sub>	3.4	4.9	6.4	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A, T <sub>J</sub> = 175°C	V <sub>CE(sat)</sub>	-	1.6 1.95	2.1 -	V
DYNAMIC CHARACTERISTICS		•		•	•	
Input capacitance	V <sub>CE</sub> = 30 V,	C <sub>ies</sub>	-	4617	_	pF
Output capacitance	$V_{GE} = 0 \text{ V},$ $f = 1 \text{ MHz}$	C <sub>oes</sub>	-	152	-	
Reverse transfer capacitance		C <sub>res</sub>	-	13	-	1
Gate charge total	V <sub>CE</sub> = 400 V,	Qg	-	136	-	nC
Gate-to-emitter charge	I <sub>C</sub> = 75 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>	-	25	_	1
Gate-to-collector charge		$Q_{gc}$	-	32	_	1
SWITCHING CHARACTERISTICS, INDUC	TIVE LOAD	•		-	•	
Turn-on delay time	$T_{C} = 25^{\circ}C,$	t <sub>d(on)</sub>	-	21	_	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 37.5 \text{ A},$ $R_{G} = 4.7 \Omega,$ $V_{GE} = 15 \text{ V},$	t <sub>r</sub>	-	16	_	1
Turn-off delay time		t <sub>d(off)</sub>	-	113	_	1
Fall time	Inductive Load	t <sub>f</sub>	-	8	_	1
Turn-on switching loss		E <sub>on</sub>	-	0.77	_	mJ
Turn-off switching loss		E <sub>off</sub>	-	0.23	_	1
Total switching loss		E <sub>ts</sub>	-	1.0	_	1
Turn-on delay time	T <sub>C</sub> = 25°C,	t <sub>d(on)</sub>	-	24	-	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 75 \text{ A},$ $R_{G} = 4.7 \Omega,$ $V_{GE} = 15 \text{ V},$ Inductive Load	t <sub>r</sub>	-	44	-	1
Turn-off delay time		t <sub>d(off)</sub>	-	106	_	1
Fall time		t <sub>f</sub>	-	68	-	1
Turn-on switching loss		E <sub>on</sub>	-	2.12	_	mJ
Turn-off switching loss		E <sub>off</sub>	-	1.14	-	1
Total switching loss		E <sub>ts</sub>	-	3.26	_	1

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, IN	DUCTIVE LOAD	•		•		
Turn-on delay time	T <sub>C</sub> = 175°C,	t <sub>d(on)</sub>	_	20	-	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 37.5 \text{ A},$	t <sub>r</sub>	_	19	-	
Turn-off delay time	$R_G = 4.7 \Omega,$ $V_{GE} = 15 V,$	t <sub>d(off)</sub>	_	124	-	
Fall time	Inductive Load	t <sub>f</sub>	_	7.7	-	
Turn-on switching loss	7	E <sub>on</sub>	_	1.52	-	mJ
Turn-off switching loss		E <sub>off</sub>	_	0.43	-	
Total switching loss		E <sub>ts</sub>	-	1.95	-	
Turn-on delay time	T <sub>C</sub> = 175°C,	t <sub>d(on)</sub>	_	24	-	ns
Rise time	V <sub>CC</sub> = 400 V, I <sub>C</sub> = 75 A,	t <sub>r</sub>	_	45	-	
Turn-off delay time	$R_G = 4.7 \Omega,$ $V_{GE} = 15 V,$	t <sub>d(off)</sub>	-	114	-	
Fall time	Inductive Load	t <sub>f</sub>	-	76	-	
Turn-on switching loss		E <sub>on</sub>	-	3.32	-	mJ
Turn-off switching loss		E <sub>off</sub>	_	1.42	-	
Total switching loss	7	E <sub>ts</sub>	_	4.74	-	
DIODE CHARACTERISTICS						
Diode Forward Voltage	I <sub>F</sub> = 75 A, T <sub>C</sub> = 25°C	$V_{FM}$	-	1.65	2.1	V
	I <sub>F</sub> = 75 A, T <sub>C</sub> = 175°C	1	_	1.55	-	
Reverse Recovery Energy	I <sub>F</sub> = 75 A, dI <sub>F</sub> /dt = 200 A/s, T <sub>C</sub> = 175°C	E <sub>rec</sub>	-	150	-	μJ
Diode Reverse Recovery Time	I <sub>F</sub> = 75 A, dI <sub>F</sub> /dt = 200 A/s, T <sub>C</sub> = 25°C	T <sub>rr</sub>	_	75	-	ns
	I <sub>F</sub> = 75 A, dI <sub>F</sub> /dt = 200 A/s, T <sub>C</sub> = 175°C	1	-	328	-	
Diode Reverse Recovery Charge	I <sub>F</sub> = 75 A, dI <sub>F</sub> /dt = 200 A/s, T <sub>C</sub> = 25°C	Q <sub>rr</sub>	-	173	-	nC
	I <sub>F</sub> = 75 A, dI <sub>F</sub> /dt = 200 A/s, T <sub>C</sub> = 175°C	1	-	2193	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

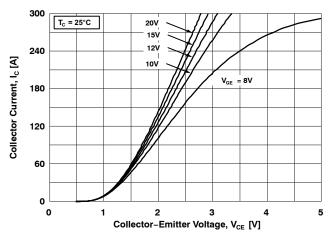


Figure 1. Typical Output Characteristics  $(T_{.I} = 25^{\circ}C)$ 

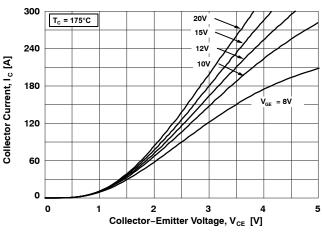


Figure 2. Typical Output Characteristics  $(T_{.1} = 175^{\circ}C)$ 

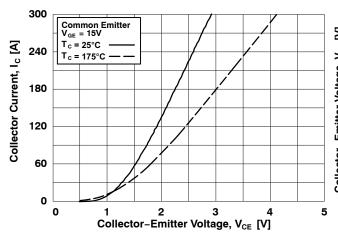


Figure 3. Typical Saturation Voltage Characteristics

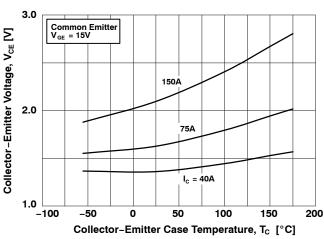


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

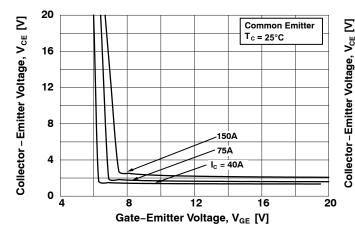


Figure 5. Saturation Voltage vs.  $V_{GE}$  ( $T_J = 25^{\circ}C$ )

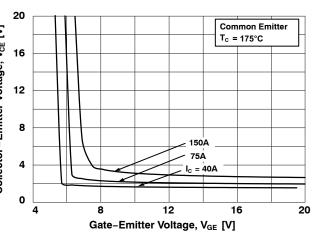


Figure 6. Saturation Voltage vs.  $V_{GE}$  (T<sub>J</sub> = 175°C)

#### TYPICAL CHARACTERISTICS (continued)

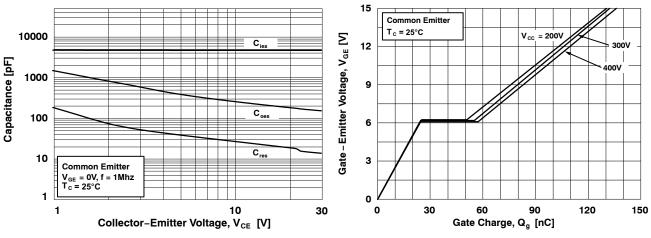


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics

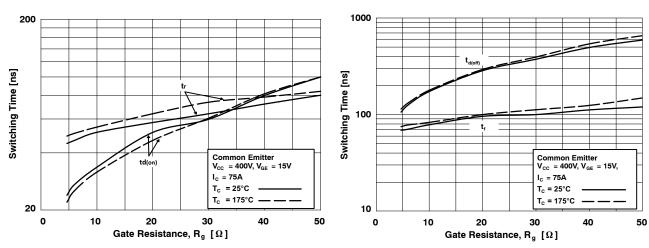


Figure 9. Turn-On Characteristics vs. Gate Resistance

Figure 10. Turn-Off Characteristics vs. Gate Resistance

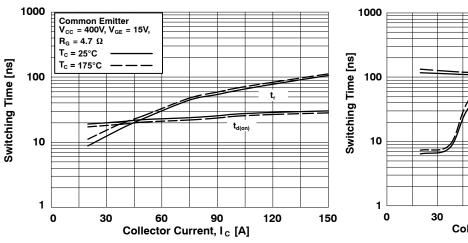


Figure 11. Turn-On Characteristics vs. Collector Current

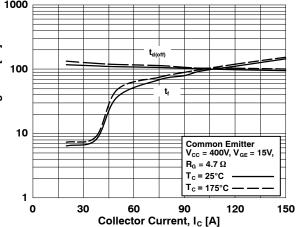
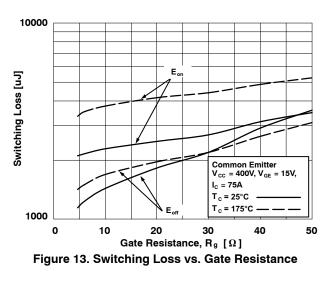


Figure 12. Turn-Off Characteristics vs. Collector Current

#### TYPICAL CHARACTERISTICS (continued)



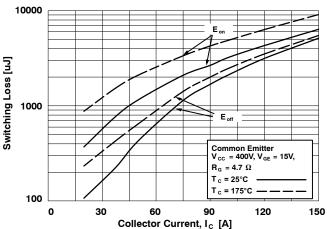


Figure 14. Switching Loss vs. Collector Current

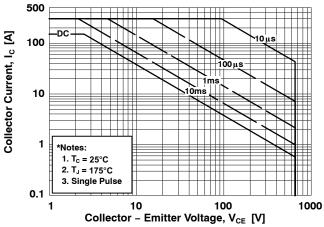


Figure 15. SOA Characteristics

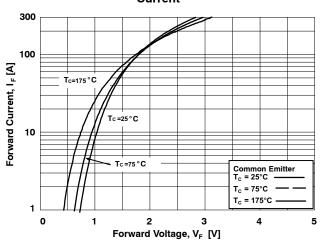


Figure 16. Forward Characteristics

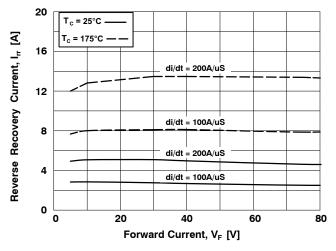


Figure 17. Reverse Recovery Current

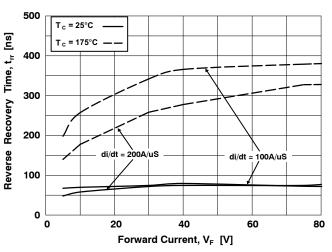


Figure 18. Reverse Recovery Time Stored Charge

## TYPICAL CHARACTERISTICS (continued)

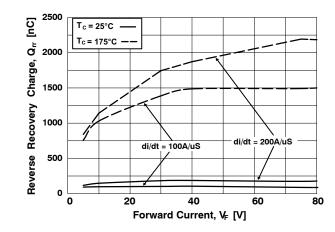


Figure 19. Stored Charge

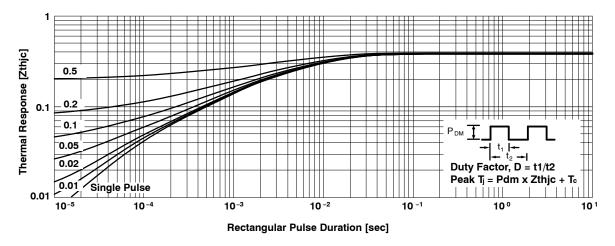


Figure 20. Transient Thermal Impedance of IGBT

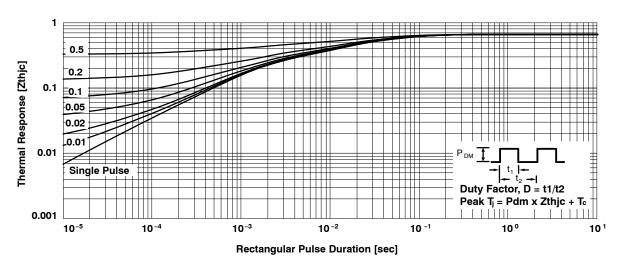
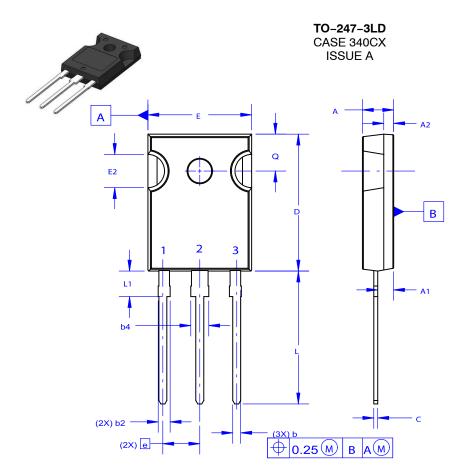
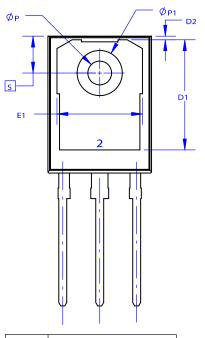


Figure 21. Transient Thermal Impedance of Diode



**DATE 06 JUL 2020** 

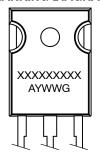


#### NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

  B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

## **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " =", may or may not be present. Some products may not follow the Generic Marking.

DIM	MIL	LIMETER	S
DIM	MIN	NOM	MAX
Α	4.58	4.70	4.82
<b>A</b> 1	2.20	2.40	2.60
A2	1.40	1.50	1.60
D	20.32	20.57	20.82
Е	15.37	15.62	15.87
E2	4.96	5.08	5.20
е	~	5.56	~
L	19.75	20.00	20.25
L1	3.69	3.81	3.93
ØΡ	3.51	3.58	3.65
Q	5.34	5.46	5.58
S	5.34	5.46	5.58
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
b4	2.42	2.54	2.66
С	0.51	0.61	0.71
D1	13.08	~	?
D2	0.51	0.93	1.35
E1	12.81	~	1
ØP1	6.60	6.80	7.00

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